



Please further amend Claim 1 as follows: Attached hereto is Appendix A showing the changes to Claim 1; language that has been added is shown underlined and language that has been deleted is in brackets.

1. (Five times amended) A semiconductor package comprising:

 a semiconductor die having front and back sides, a first electrical terminal being located on the back side, at least a second electrical terminal being located on the front side; and a leadframe in electrical contact with the first terminal, the leadframe being formed in the shape of a cup, the die being located in the cup, at least one lead of the leadframe having a portion that extends laterally to be coplanar with the front side of the die along a substantial portion of its length, and the at least one lead being in electrical contact with the first electrical terminal, the back side of the die facing in a direction toward the inside of the cup, wherein the second electrical terminal on the front side of the die is exposed for direct mounting connection on a support surface.

Please add Claim 9 as follows:

 <sup>10</sup> 9. The semiconductor package of Claim 1, further comprising a plastic capsule in contact with the outside of the cup and wherein no part of the plastic capsule extends between the lead and the support surface when the die is mounted on the support surface.